

LINEAR TECHNOLOGY MATERIALS DECLARATION

| 1t1999mpms8-10#pbf                |                                  | (Engineering Calculation) |            |                      |                               | MSOP                            |
|-----------------------------------|----------------------------------|---------------------------|------------|----------------------|-------------------------------|---------------------------------|
| (printed on: 2020-07-11 19:09:32) |                                  |                           |            |                      | TOTAL MASS (g) : 0.027152     |                                 |
| COMPONENT MATERIAL                | VENDOR/ INDUSTRY NAMES           | CONSTITUENT NAME          | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. |
| Active Device                     | Linear Technology                | Silicon (Si)              | 7440-21-3  | 0.001914             | 1000000                       | 70491.9765625                   |
| Die Coat                          | Dow Corning                      | Silicone                  | 69430-27-9 | 0.000000             | 0                             | 0                               |
| Lead Frame                        | A42                              | Copper (Cu)               | 7440-50-8  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Iron (Fe)                 | 7439-89-6  | 0.006206             | 580000                        | 228564.90625                    |
|                                   |                                  | Phosphorus (P)            | 7723-14-0  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Zinc (Zn)                 | 7440-66-6  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Nickel (Ni)               | 7440-02-0  | 0.004494             | 420000                        | 165512.515625                   |
|                                   |                                  | Silicon (Si)              | 7440-21-3  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Magnesium (Mg)            | 7439-95-4  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Tin (Sn)                  | 7440-31-5  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Lead Frame Total:         |            | 0.010700             | 1000000                       | 394077.40625                    |
| Plating                           | PMI                              | Exter. Plating Pb         | 7439-92-1  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Exter. Plating Sn         | 7440-31-5  | 0.000710             | 1000000                       | 26149.9804688                   |
|                                   |                                  | External Plating Total:   |            | 0.000710             | 1000000                       | 26149.9804688                   |
|                                   |                                  | Inter. Plating Ni         | 7440-02-0  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Inter. Plating Ag         | 7440-22-4  | 0.000086             | 1000000                       | 3167.35107422                   |
|                                   |                                  | Internal Plating Total:   |            | 0.000086             | 1000000                       | 3167.35107422                   |
| Die Attach                        | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag)               | 7440-22-4  | 0.000669             | 750000                        | 24639.0449219                   |
|                                   |                                  | Tin (Sn)                  | 7440-31-5  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Lead (Pb)                 | 7439-92-1  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Silica (SiO2)             | 60676-86-0 | 0.000000             | 0                             | 0                               |
|                                   |                                  | Indium (In)               | 7440-74-6  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Metal Oxide               |            | 0.000000             | 0                             | 0                               |
|                                   |                                  | Antimony (Sb)             | 7440-36-0  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Resin (EP)                |            | 0.000223             | 250000                        | 8213.015625                     |
|                                   |                                  | Die Attach Total:         |            | 0.000892             | 1000000                       | 32852.0625                      |
| Encapsulation                     | MULTI-AROMATIC RESIN Br/Sb FREE  | Resin (EP)                |            | 0.001659             | 130000                        | 61100.4140625                   |
|                                   |                                  | Bromine (Br)              | 40039-93-8 | 0.000000             | 0                             | 0                               |
|                                   |                                  | Silica (SiO2)             | 60676-86-0 | 0.010591             | 830000                        | 390063                          |
|                                   |                                  | Antimony Trioxide (Sb2O3) | 1309-64-4  | 0.000000             | 0                             | 0                               |
|                                   |                                  | Metal Hydroxide           |            | 0.000447             | 35000                         | 16462.8613281                   |
|                                   |                                  | Carbon Black (C)          | 1333-86-4  | 0.000064             | 5000                          | 2357.09838867                   |
|                                   |                                  | Encapsulation Total:      |            | 0.012761             | 1000000                       | 469983.34375                    |
| Bond Wire Estimated               | AFW/TANAKA/ Kn                   | Gold (Au)                 | 7440-57-5  | 0.000089             | 1000000                       | 3277.84008789                   |
|                                   |                                  |                           |            |                      | TOTAL MASS (g) :              | 0.027152                        |